

Tek Pak Announces Partnership with XGR Technologies

April 1, 2019

Tek Pak is proud to announce a strategic partnership with XGR Technologies to produce and supply SnapShot® board level metallized Electro Magnetic Interference (EMI) shields. For the past 13 years Tek Pak had been producing SnapShot shields for W.L. Gore under an exclusive supplier agreement. In January 2019, XGR completed the acquisition of the intellectual property and manufacturing assets for the SnapShot product line from W.L. Gore. In a parallel move, Tek Pak purchased all the metallizing equipment and patents necessary to manufacture the metalized plastic substrate required to make SnapShot shields. These two acquisitions have secured the entire product supply chain, thus ensuring uninterrupted supply of SnapShot EMI shields

SnapShot EMI shields are a board level alternative to permanent soldered metal cans or shields. SnapShot shields offer superior shielding performance and reliability with greater design flexibility. The shields attach easily, install after the SMT reflow and inspection processes, and are easily removable by hand.

The collaboration between XGR and Tek Pak will bring a new level of focus, security, and service in the production of the SnapShot product line. The team at XGR Technologies includes a co-inventor named on the original SnapShot patents, so clients can be assured the necessary expertise for shielding applications will continue. While Tek Pak, a company with over twenty-five years of service to the electronics industry, will continue to leverage their expertise in custom production in electronics packaging and rapid prototyping, from design to production, in as little as one week. Attached is information on our exclusive partner and the product being sold through XGR Technologies.